

RELIABILITY REPORT





Reliability Data Report

Product Family R566

LTC2862 / LTC2863 / LTC2864 / LTC2865 /
LTC2874 / LTC2875 / LTC2876 / LTC2877

Reliability Data Report

Report Number: R566

Report generated on: Mon May 02 14:47:07 PDT 2016

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2, 3}
SOIC/MSOP	320	1116	1416	881	0
Totals	320	-	-	881	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	50	1250	1250	1	0
SOIC/MSOP	331	1431	1519	24	0
Totals	381	-	-	25	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	50	1250	1250	5	0
SOIC/MSOP	330	1431	1519	33	0
Totals	380	-	-	38	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	50	1250	1250	5	0
SOIC/MSOP	327	1431	1519	32	0
Totals	377	-	-	37	0

(1) Assumes Activation Energy = 0.7 Electron Volts
 (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =13.45 FITS
 (3) Mean Time Between Failure in Years = 8487.66
 Note: 1 FIT = 1 Failure in One Billion Hours.
 Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning